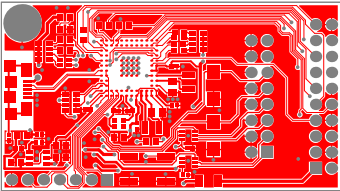


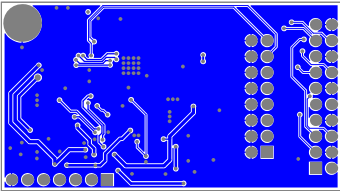
Top Copper



XMOS LTD = XPCB-068 = 1V2B = 25 Feb 2014

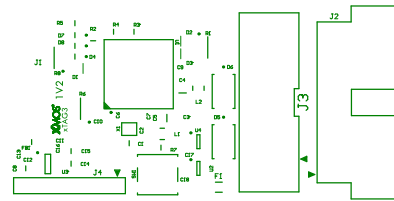
TOP COPPER LAYER

Bottom Copper



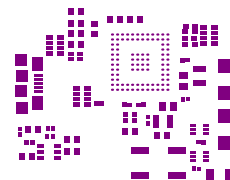
XMOS LTD = XPCB-068 = 1V2B = 25 Feb 2014

BOTTOM COPPER LAYER



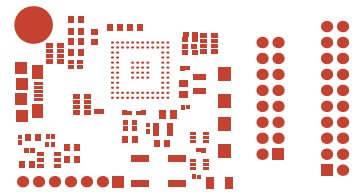
TOP SILKSCREEN LAYER

BOTTOM SILKSCREEN LAYER

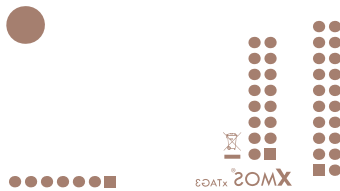


TOP PASTE LAYER

BOTTOM PASTE LAYER



TOP SOLDER MASK LAYER



BOTTOM SOLDER MASK LAYER

PCB Manufacturing Notes

General Info

Board dimensions - 54mm x 30mm
Number of layers - 2
Smallest hole - 0.3mm
Number of holes - Approx 150
Minimum Track & Gap - 0.15mm
RoHS/Lead Free - Yes
Material - FR4

Stackup

Stackup is to be as follows:

| | |
|-------|-----------------------------|
| Layer | Copper Weight (Pre-Plating) |
| | 0.5oz |
| | 0.5oz |

Finished board thickness to be 1.6mm ± 0.1mm

Impedance Control

None required

Copper Thieving/Balancing

The supplier may add copper thieving/balancing if required.

Finish

A.) Conductive finish

Plating to be immersion gold.

B.) Soldermask

Liquid photo imageable soldermask (BLACK). Pads have not been oversized.

Supplier should oversize soldermask on pads to suit process.

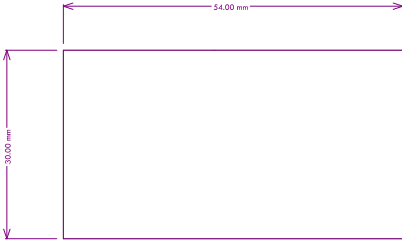
C.) Silkscreen

Colour white. Supplier should remove any silkscreen which overhangs pads.

Drill Data

Drill data is in Excellon format, metric (000.000), no zero suppression, absolute coordinates.

Hole size is finished size.



FABRICATION INSTRUCTIONS



| | | |
|----------------|----------|----------|
| Project Name | | |
| XPCB-06B xTAG3 | | |
| Sheet | Date | Revision |
| A4 | FEB 2014 | 1V2B |

PCB Manufacturing Notes

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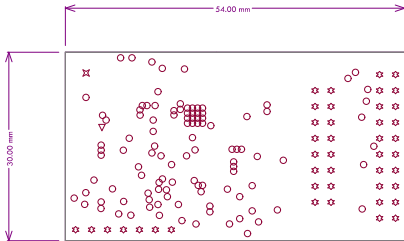
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Hole size is finished size.



FABRICATION INSTRUCTIONS DRILL DRAWING

| Symbol | Hit Count | Tool Size | Plated | Hole Type |
|--------|-----------|--------------------|--------|-----------|
| ○ | 109 | 0.3mm (11.811mil) | PTH | Round |
| ▽ | 1 | 0.5mm (19.685mil) | PTH | Round |
| ☆ | 43 | 1mm (39.37mil) | PTH | Round |
| ✕ | 1 | 3.2mm (125.984mil) | PTH | Round |
| | 154 Total | | | |

Drill Drawing.

| | | |
|--|----------|----------|
| XMOS | | |
| Project Name | | |
| XPCB-06B xTAG3 | | |
| Sheet | Date | Revision |
| A4 | FEB 2014 | 1V2B |
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